Materials Declaration

Package	LFCSP
Body Size	3 X 3 X 0.75 mm
LeadCount	10
Option	Pb-free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica Fused	93.70	1.03E-02	464515
Epoxy Resin	3.00	3.30E-04	14872
Phenol Resin	3.00	3.30E-04	14872
Carbon Black	0.30	3.30E-05	1487
Subtotal		1.10 E-02	495747

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	1.02 E-02	459235
Fe	2.35	2.38 E-04	10726
Zn	0.12	1.32 E-05	594
P	0.03	2.53 E-06	114
Subtotal		1.04 E-02	470670

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.05 E-04	4754

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	1.31 E-04	5909

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.0	9.90 E-05	4466
Pd	1.0	1.00 E-06	45
Subtotal		1.00 E-04	4511

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.78 E-04	17056

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	85.0	2.55 E-05	1150
Acrylates	5.0	1.50 E-06	68
Bismaleimide	5.0	1.50 E-06	68
Additive	5.0	1.50 E-06	68
Subtotal		3.00 E-05	1353

Package Totals

Weight (g)	PPM
2.22 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS.
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	3.7	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS.
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ADI Proprietary

Materials Declaration

Package	LFCSP
Body Size	3 X 3 X 0.75 mm
LeadCount	10
Option	SnPb

Molding Compound

Item	% of Compound	Weight (g)	PPM
Silica Fused	93.70	1.03E-02	464326
Epoxy Resin	3.00	3.30E-04	14866
Phenol Resin	3.00	3.30E-04	14866
Carbon Black	0.30	3.30E-05	1487
Subtotal		1.10 E-02	495546

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	97.50	1.02 E-02	459049
Fe	2.35	2.38 E-04	10722
Zn	0.12	1.32 E-05	594
P	0.03	2.53 E-06	114
Subtotal		1.04 E-02	470479

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	1.05 E-04	4753

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	1.19 E-04	5366
Pb	15.0	2.10 E-05	947
Subtotal		1.40 E-04	6313

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.0	9.90 E-05	4464
Pd	1.0	1.00 E-06	45
Subtotal		1.00 E-04	4509

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.78 E-04	17049

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag	85.0	2.55 E-05	1150
Acrylates	5.0	1.50 E-06	68
Bismaleimide	5.0	1.50 E-06	68
Additive	5.0	1.50 E-06	68
Subtotal		3.00 E-05	1353

Package Totals

Weight (g)	PPM
2.22 E-02	1000000

Molding Compound

Item	PPM	Method
Pb	Not Detected	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS.
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Die Attach Paste

Item	PPM	Method
Pb	3.7	US EPA 3052. ICP-OES
Cd	Not Detected	US EPA 3052. ICP-OES
Hg	Not Detected	US EPA 3052. ICP-OES
Cr+6	Not Detected	US EPA 3060A & 7196A. UV-VIS.
PBB	Not Detected	Analysis performed by GC/MS
PBDE	Not Detected	Analysis performed by GC/MS

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.